

# Thyristor Module

$V_{RRM} = 2 \times 1800 \text{ V}$

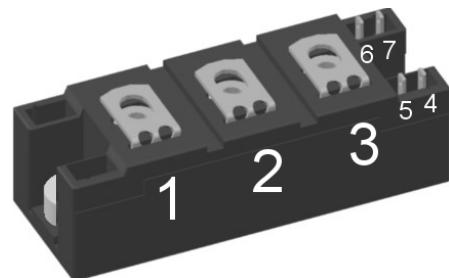
$I_{TAV} = 160 \text{ A}$

$V_T = 1.09 \text{ V}$

## Phase leg

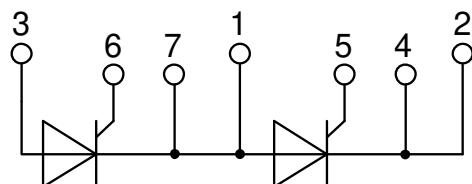
### Part number

**MCMA160P1800YA-MI**



Backside: isolated

 E72873



### Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al<sub>2</sub>O<sub>3</sub>-ceramic

### Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

### Package: Y4

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

### Disclaimer Notice

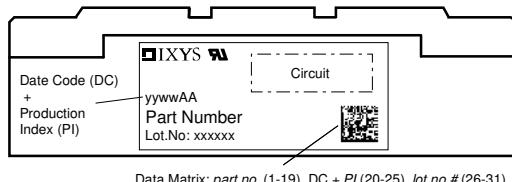
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**Thyristor**

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1900	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ\text{C}$			1800	V
$I_{R/D}$	reverse current, drain current	$V_{R/D} = 1800 \text{ V}$ $V_{R/D} = 1800 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 140^\circ\text{C}$		200 10	$\mu\text{A}$ mA
$V_T$	forward voltage drop	$I_T = 160 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$		1.14	V
		$I_T = 320 \text{ A}$			1.35	V
		$I_T = 160 \text{ A}$ $I_T = 320 \text{ A}$	$T_{VJ} = 125^\circ\text{C}$		1.09 1.35	V
$I_{TAV}$	average forward current	$T_C = 85^\circ\text{C}$	$T_{VJ} = 140^\circ\text{C}$		160	A
$I_{T(RMS)}$	RMS forward current	180° sine			250	A
$V_{TO}$	threshold voltage	$r_T$ slope resistance } for power loss calculation only	$T_{VJ} = 140^\circ\text{C}$		0.82	V
	slope resistance				1.63	$\text{m}\Omega$
$R_{thJC}$	thermal resistance junction to case				0.21	K/W
$R_{thCH}$	thermal resistance case to heatsink			0.11		K/W
$P_{tot}$	total power dissipation		$T_C = 25^\circ\text{C}$		550	W
$I_{TSM}$	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$		4.75	kA
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 \text{ V}$		5.13	kA
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 140^\circ\text{C}$		4.04	kA
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 \text{ V}$		4.36	kA
$I^2t$	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ\text{C}$		112.8	$\text{kA}^2\text{s}$
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 \text{ V}$		109.5	$\text{kA}^2\text{s}$
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 140^\circ\text{C}$		81.6	$\text{kA}^2\text{s}$
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 \text{ V}$		79.1	$\text{kA}^2\text{s}$
$C_J$	junction capacitance	$V_R = 400 \text{ V}$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ\text{C}$	211		pF
$P_{GM}$	max. gate power dissipation	$t_p = 30 \mu\text{s}$	$T_C = 140^\circ\text{C}$		120	W
		$t_p = 500 \mu\text{s}$			60 8	W
$P_{GAV}$	average gate power dissipation					
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 140^\circ\text{C}; f = 50 \text{ Hz}$ repetitive, $I_T = 480 \text{ A}$			150	$\text{A}/\mu\text{s}$
		$t_p = 200 \mu\text{s}; di_G/dt = 0.5 \text{ A}/\mu\text{s};$				
		$I_G = 0.5 \text{ A}; V = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 160 \text{ A}$			260	$\text{A}/\mu\text{s}$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 140^\circ\text{C}$		1000	$\text{V}/\mu\text{s}$
		$R_{GK} = \infty$ ; method 1 (linear voltage rise)				
$V_{GT}$	gate trigger voltage	$V_D = 6 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$		2.5	V
			$T_{VJ} = -40^\circ\text{C}$		2.6	V
$I_{GT}$	gate trigger current	$V_D = 6 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$		150	mA
			$T_{VJ} = -40^\circ\text{C}$		200	mA
$V_{GD}$	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 140^\circ\text{C}$		0.2	V
$I_{GD}$	gate non-trigger current				10	mA
$I_L$	latching current	$t_p = 30 \mu\text{s}$ $I_G = 0.5 \text{ A}; di_G/dt = 0.5 \text{ A}/\mu\text{s}$	$T_{VJ} = 25^\circ\text{C}$		300	mA
$I_H$	holding current	$V_D = 6 \text{ V}$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ\text{C}$		200	mA
$t_{gd}$	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$ $I_G = 0.5 \text{ A}; di_G/dt = 0.5 \text{ A}/\mu\text{s}$	$T_{VJ} = 25^\circ\text{C}$		2	$\mu\text{s}$
$t_q$	turn-off time	$V_R = 100 \text{ V}; I_T = 160 \text{ A}; V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ\text{C}$ $di/dt = 10 \text{ A}/\mu\text{s}$ $dv/dt = 20 \text{ V}/\mu\text{s}$ $t_p = 200 \mu\text{s}$		150		$\mu\text{s}$

**Package Y4**

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$I_{RMS}$	RMS current	per terminal			300	A
$T_{VJ}$	virtual junction temperature		-40		140	°C
$T_{op}$	operation temperature		-40		125	°C
$T_{stg}$	storage temperature		-40		125	°C
<b>Weight</b>				150		g
$M_D$	mounting torque		2.25		2.75	Nm
$M_T$	terminal torque		4.5		5.5	Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	14.0	10.0		mm
$d_{Spb/Apb}$		terminal to backside	16.0	16.0		mm
$V_{ISOL}$	isolation voltage	t = 1 second t = 1 minute	3600 50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3000		V V



Data Matrix: part no. (1-19), DC + PI (20-25), lot.no.# (26-31), blank (32), serial no.#(33-36)

**Part description**

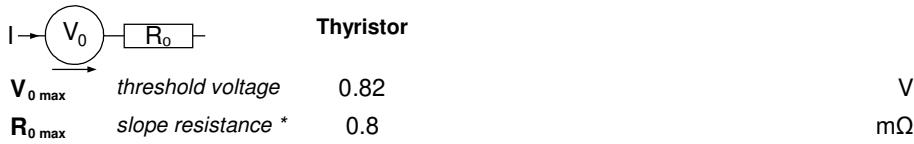
M = Module  
C = Thyristor (SCR)  
M = Thyristor  
A = (up to 1800V)  
160 = Current Rating [A]  
P = Phase leg  
1800 = Reverse Voltage [V]  
YA = Y4-M6  
- = Hyphen  
MI = with metal inserts

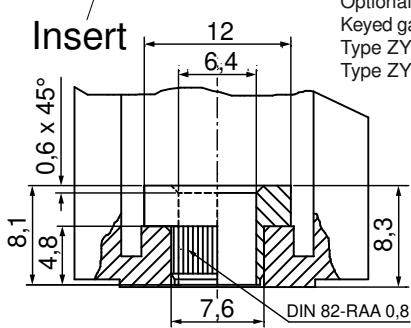
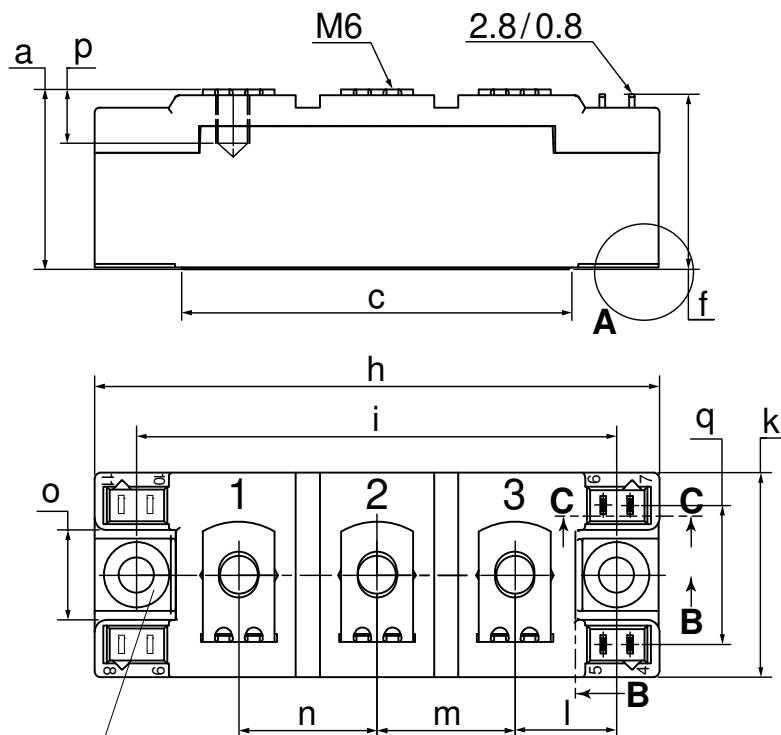
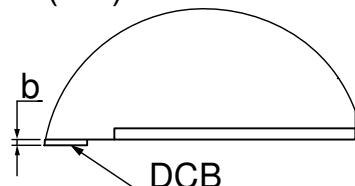
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCMA160P1800YA-MI	MCMA160P1800YA-MI	Box	6	524875

**Equivalent Circuits for Simulation**

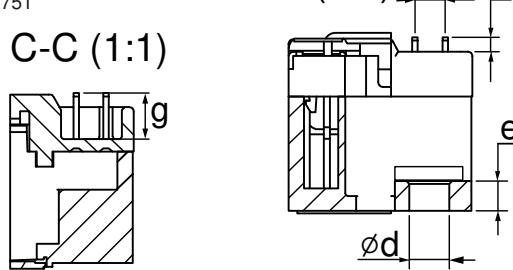
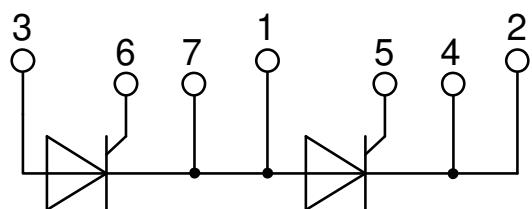
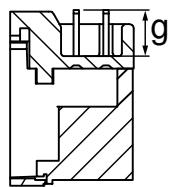
\* on die level

$T_{VJ} = 140$  °C



**Outlines Y4**

**A (3:1)**


Dim.	MIN [mm]	MAX [mm]	MIN [inch]	MAX [inch]
a	30.0	30.6	1.181	1.205
b	typ. 0.25		typ. 0.010	
c	64.0	65.0	2.520	2.559
d	typ. 6.4		typ. 0.250	
e	4.9	5.1	0.193	0.201
f	28.6	29.2	1.126	1.150
g	7.3	7.7	0.287	0.303
h	93.5	94.5	3.681	3.720
i	79.5	80.5	3.130	3.169
j	4.8	5.2	0.189	0.205
k	33.4	34.0	1.315	1.339
l	16.7	17.3	0.657	0.681
m	22.7	23.3	0.894	0.917
n	22.7	23.3	0.894	0.917
o	14.0	15.0	0.551	0.591
p	typ. 10.5		typ. 0.413	
q	22.8	23.3	0.898	0.917
r	1.8	2.4	0.071	0.041

**B-B (1:1)**

**C-C (1:1)**


## Thyristor

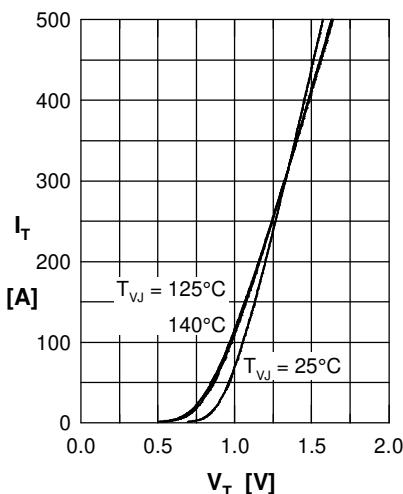


Fig. 1 Forward current vs.  
voltage drop per thyristor

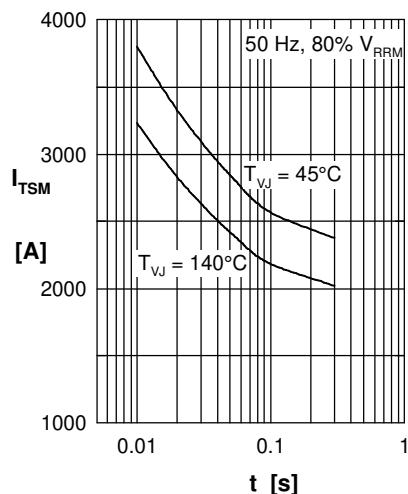


Fig. 2 Surge overload current  
vs. time per thyristor

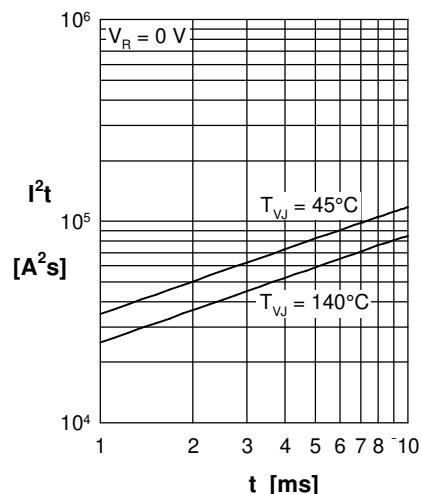


Fig. 3  $I^2t$  vs. time per thyristor

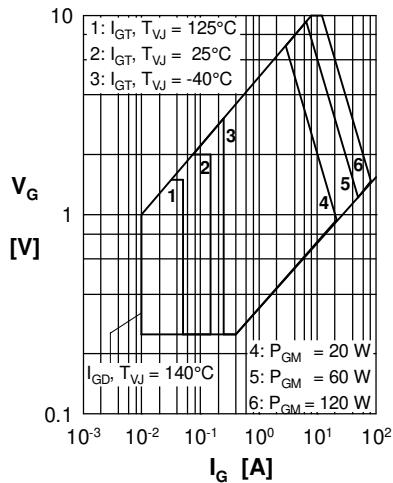


Fig. 4 Gate voltage & gate current

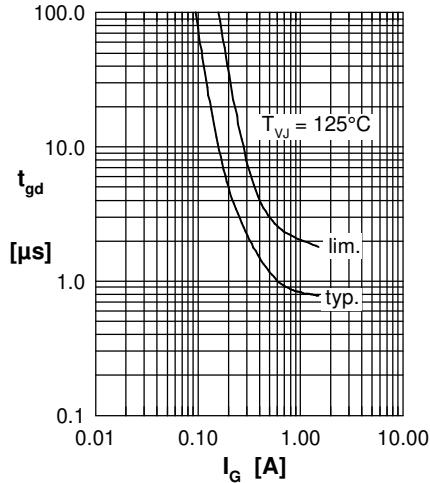


Fig. 5 Gate controlled delay time  $t_{gd}$

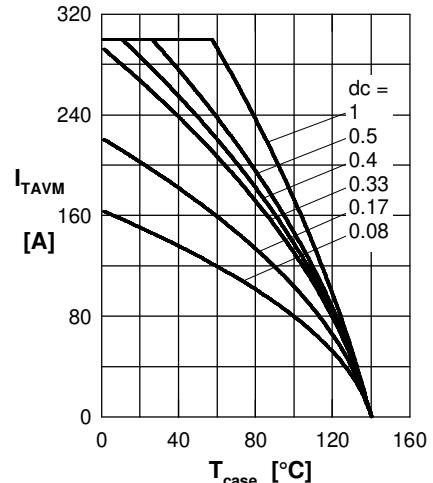


Fig. 6 Max. forward current vs.  
case temperature per thyristor

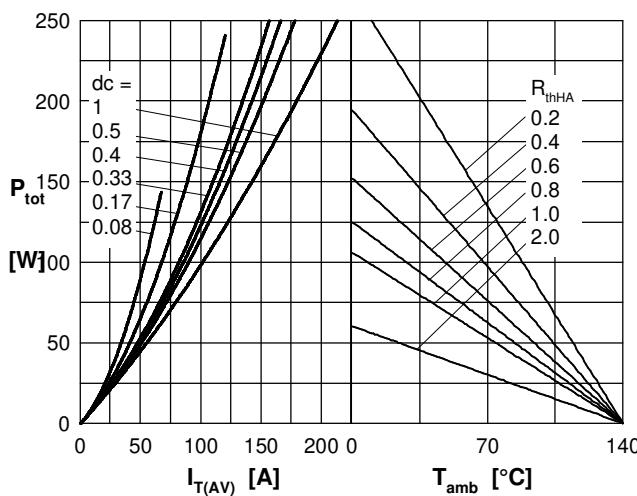


Fig. 7 Power dissipation vs. forward current  
and ambient temperature per thyristor

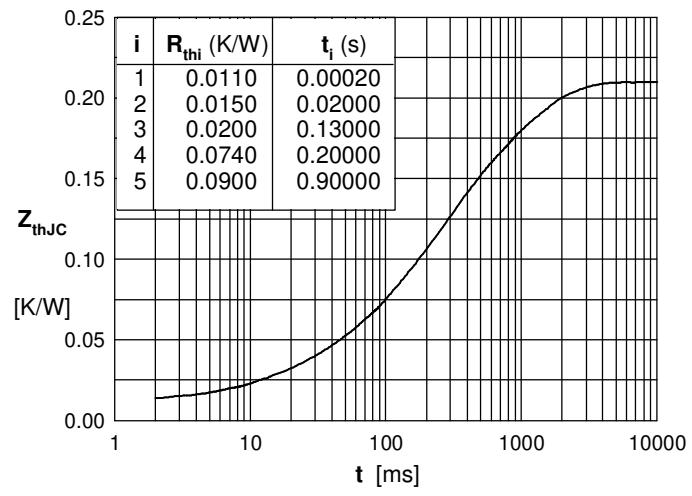


Fig. 8 Transient thermal impedance junction to case  
vs. time per thyristor